

Excellent Integrated System Limited

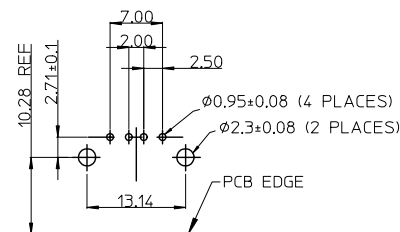
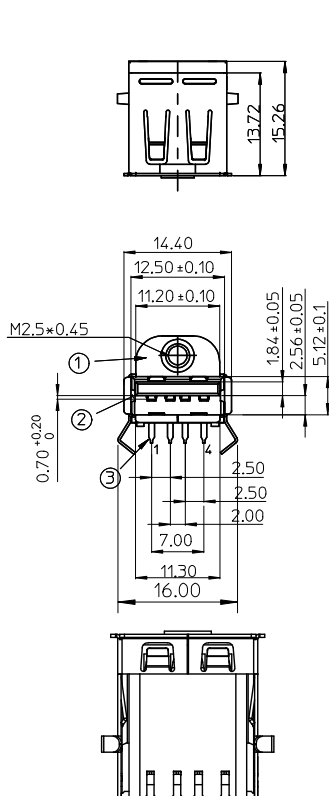
Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

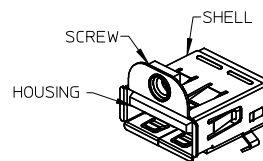
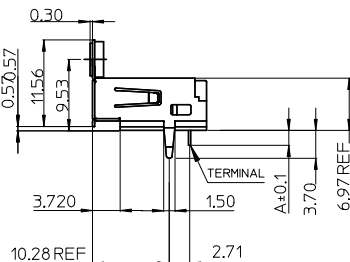
[Molex Connector Corporation](#)
[0676432991](#)

For any questions, you can email us directly:

sales@integrated-circuit.com



PCB LAYOUT (BOTTOM VIEW)



NOTES:

1. MATERIAL:
① METAL SHELL: COPPER ALLOY, SCREW: BRASS
② HOUSING: SEE CHART, 30% GLASS FIBER FILLES, UL94-V0.
③ TERMINAL: PHOSPHOR BRONZE
2. PLATING:
TERMINAL:
CONTACT AREA: (a) GOLD FLASH.
(b) GOLD (Au), THICKNESS=0.76 μ M/304NCH MINIMUM.
SOLDER TAIL: TIN PLATED, THICKNESS=1.875 μ M/754NCH MINIMUM.
UNDER PLATED: NICKEL (Ni), THICKNESS=1.25 μ M/504NCH MINIMUM.
METAL SHELL: SEE CHART.
3. RECOMMENDED PCB THICKNESS: SEE CHART
4. PRODUCT SPECIFICATION: FOR IR REFER TO PS-67643-002
FOR NON IR REFER TO PS-67643-003
5. TORQUE FORCE SPEC: 2.50kg-cm Min, MEASURED AT BROKEN POINT.
6. TEST SUMMARY: FOR IR REFER TO TS-67643-002
FOR NON IR REFER TO TS-67643-003
7. PACKAGE: REFER TO PK-67643-002
8. LEAD FREE AND ROHS COMPLIANCE PRODUCT

REVISED	EC NO:	DRWN: FANG05	CHKD:	APPR:	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	TITLE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
							mm	INCH								
2013/05/09						$\nabla=0$ $\nabla=0$	4 PLACES $\pm$ ---	$\pm$ ---	MM ONLY	1:1	METRIC		USB A TYPE RCPT SGL RA THRHOLE WITH UPPER FLG (LEAD-FREE VERSION)			1 OF 2
							3 PLACES $\pm$ ---	$\pm$ ---								
							2 PLACES $\pm$ 0.25	$\pm$ ---								
							1 PLACE $\pm$ 0.25	$\pm$ ---								
							ANGULAR $\pm$ 3°									
							DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									
							SEE SHEET 2									
							THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0990	POLYESTER	BLACK	GOLD FLSAH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=2.54 μM/100MNCH UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	NON IR
67643-1990	POLYESTER	WHITE			REFLOW PROCESS
67643-2990	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3990	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
67643-0991	POLYESTER	BLACK	GOLD PLATING 0.76 μM/30MNCH	NON IR REFLOW PROCESS: MATTE TIN PLATED. THICKNESS=2.00 μM/80MNCH UNDER PLATE:NICKEL (Ni).	NON IR
67643-1991	POLYESTER	WHITE			REFLOW PROCESS
67643-2991	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3991	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
PCB THICKNESS		1.60±0.05			
DIMENSION "A"		2.60			

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0980	HIGH TEMPERATURE NYLON	BLACK	GOLD FLSAH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=2.54 μM/100μMNC UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	FOR IR REFLOW PROCESS
67643-1980	HIGH TEMPERATURE NYLON	WHITE			
67643-0981	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING 0.76 μM/30μMNC		
67643-1981	HIGH TEMPERATURE NYLON	WHITE			
PCB THICKNESS		1.20±0.05			
DIMENSION "A"		2.00			

REVISED EC NO: DRAWN BY: YANG05 CHKD: APPR:	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	TITLE USB A TYPE RCPT SGL RA THRHOLE WITH UPPER FLG (LEAD-FREE VERSION)			
				mm	INCH	DRAWN BY IVY-LIN	DATE 2005/04/01	MOLEX MOLEX INCORPORATED					
			4 PLACES	±---	±---	CHECKED BY	DATE						
			3 PLACES	±---	±---	ALL IN	2005/04/01						
			2 PLACES	±0.25	±---	APPROVED BY	DATE						
			1 PLACE	±0.25	±---	WWSCHANG	2005/04/01						
			ANGULAR ± 3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.				
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-67643-004		2 OF 2				
					SIZE A4	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							